

Data Sheet 1336 Rev.B

Features

- Glass Passivated Die Construction
- Low Reverse Leakage Current
- Low Power Loss, High Efficiency
- Electrically Isolated Epoxy Case for Maximum Heat Dissipation
- Case to Terminal Isolation Voltage 2500V
- UL Recognized File # E223064

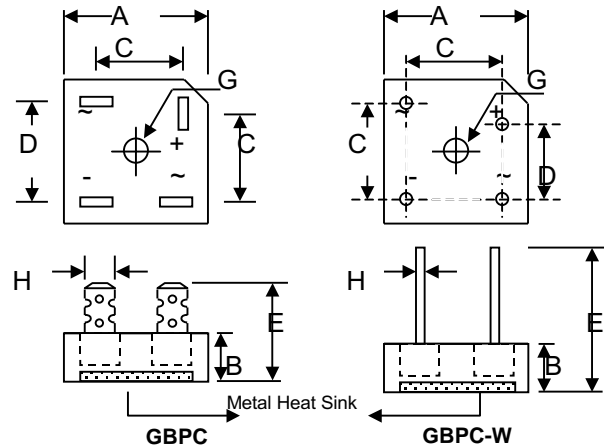
Mechanical Data

- Case: Epoxy Case with Heat Sink Internally Mounted in the Bridge Encapsulation
- Terminals: Plated Leads Solderable per MIL-STD-202, Method 208
- Polarity: Symbols Marked on Case
- Mounting: Through Hole for #8 Screw
- Weight: GBPC 24 grams (approx.)
GBPC-W 21 grams (approx.)
- Marking: Type Number

"W" Suffix Designates Wire Leads

No Suffix Designates Faston Terminals

*All Models are Available on B(Height)=7.62mm Max. Epoxy Case



	GBPC		GBPC-W	
Dim	Min	Max	Min	Max
A	28.40	28.70	28.40	28.70
B	10.97	11.23	10.97	11.23
C	15.70	16.70	17.10	19.10
D	17.50	18.50	10.90	11.90
E	22.86	25.40	30.50	—
G	Hole for #8 screw, 4.90Ø Nominal			
H	6.35 Typical		0.97Ø	1.07Ø
All Dimension in mm				

Maximum Ratings and Electrical Characteristics @T_A=25°C unless otherwise specified

Single Phase, half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

Characteristic	Symbol	GBPC 1000/W	GBPC 1001/W	GBPC 1002/W	GBPC 1004/W	GBPC 1006/W	GBPC 1008/W	GBPC 1010/W	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	50	100	200	400	600	800	1000	V
RMS Reverse Voltage	V _{R(RMS)}	35	70	140	280	420	560	700	V
Average Rectified Output Current @T _A = 50°C	I _O	10							A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}	200							A
Forward Voltage (per element) @I _F = 5.0A	V _{FM}	1.1							V
Peak Reverse Current @T _C = 25°C At Rated DC Blocking Voltage @T _C = 125°C	I _{RM}	5.0 500							µA
Typical Junction Capacitance (Note 1)	C _j	300							pF
Typical Thermal Resistance (Note 2)	R _{θJC}	5.3							K/W
RMS Isolation Voltage from Case to Lead	V _{ISO}	2500							V
Operating and Storage Temperature Range	T _J , T _{STG}	-65 to +150							°C

Note: 1. Measured at 1.0 MHz and applied reverse voltage of 4.0V D.C.

2. Thermal resistance junction to case per element mounted on heatsink.

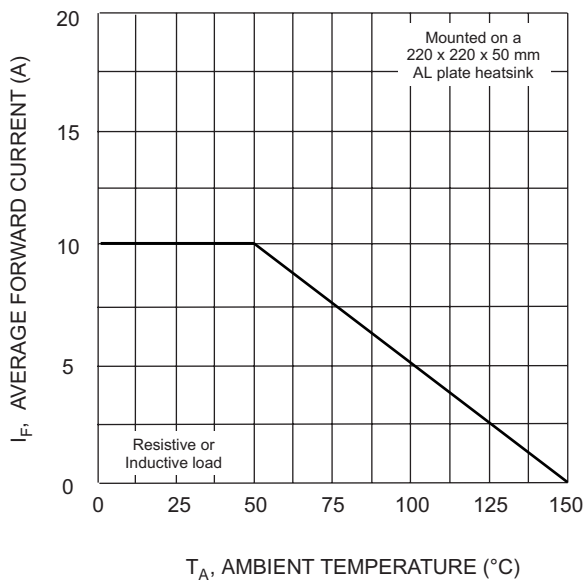


Fig. 1 Forward Current Derating Curve

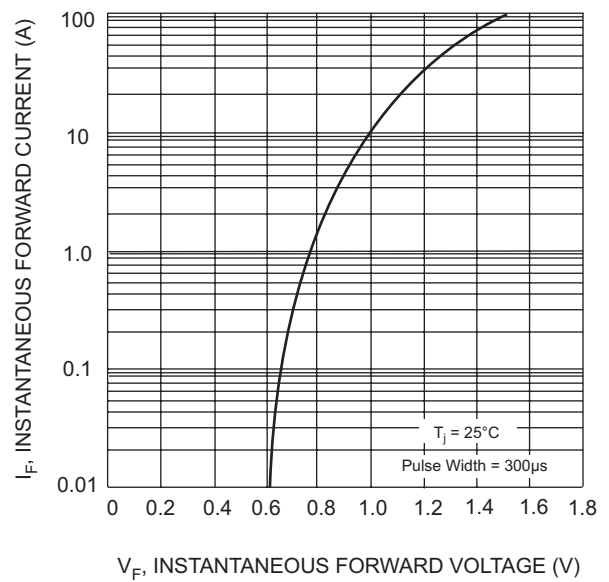


Fig. 2 Typical Forward Characteristics (per element)

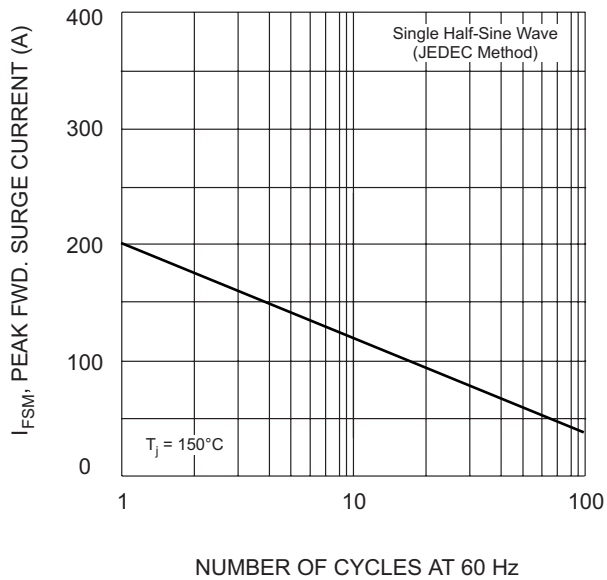


Fig. 3 Max Non-Repetitive Surge Current

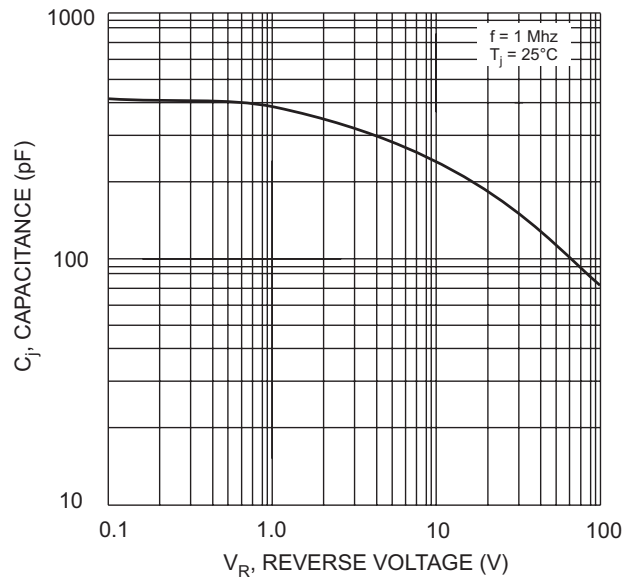


Fig. 4 Typical Junction Capacitance (per element)

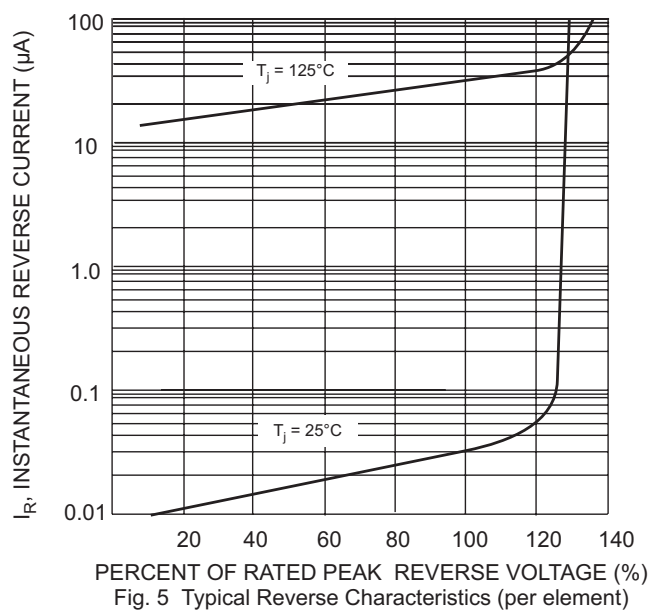


Fig. 5 Typical Reverse Characteristics (per element)

TECHNICAL DATA

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